


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F756BGT6	40UH*449XXZ	A	9998	2017-04-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	2542.17	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	28x28x1.4	208	L Bend	
Comment	Package : UH LQFP 208 28x28x1.4 1.0 7147657			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH- 7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	40UH*449XXXZ				6999999.0	0.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	19.433	mg	supplier	die	Silicon (Si)	7440-21-3		18.185	mg	935779	7153
				supplier	metallization	Aluminium (Al)	7429-90-5		0.087	mg	4477	34
				supplier	metallization	Copper (Cu)	7440-50-8		0.567	mg	29177	223
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	103	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.079	mg	4065	31
				supplier	metallization	Tungsten (W)	7440-33-7		0.255	mg	13122	100
				supplier	Passivation	Silicon Nitride	12033-89-5		0.066	mg	3396	26
LEADFRAME (LGIC- C194)	M-011 Other inorganic materials	471.813	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.192	mg	9880	76
				supplier	ALLOY	Copper (Cu)	7440-50-8		459.783	mg	974502	180862
				supplier	ALLOY	Iron (Fe)	7439-89-6		11.323	mg	23999	4454
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.566	mg	1199	223
				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.141	mg	299	56
LEADFRAME (LGIC- Ag)	M-011 Other inorganic materials	2.250	mg	supplier	COATING	Silver(Ag)	7440-22-4		2.250	mg	1000000	885
DIE ATTACH (Evertech -AP4200)	M-011 Other inorganic materials	2.842	mg	supplier	GLUE	Epoxy	9003-36-5		0.625	mg	219916	246
				supplier	GLUE	Silver(Ag)	7440-22-4		2.217	mg	780084	872
BONDING WIRE (Heraeus - HTS Au w/)	M-011 Other inorganic materials	5.737	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		5.679	mg	989890	2234
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.058	mg	10110	23
ENCAPSULATION (Sumitomo -G631H)	M-011 Other inorganic materials	2028.745	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		206.951	mg	102068	81407
				supplier	MOLDING COMPOUND	Silica fused (SiO3)	60676-86-0		1697.623	mg	836692	-332216
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		113.823	mg	56137	44774
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		10.348	mg	5104	4071
FINISHING- (ST380 -Sn)	M-011 Other inorganic materials	11.350	mg	supplier	EXTERNAL PLATING	Tin (Sn)	7440-31-5		11.350	mg	1000000	4465